

Why would you need a 500Amp MOSFET?

Introduction

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- International Product Marketing Manager



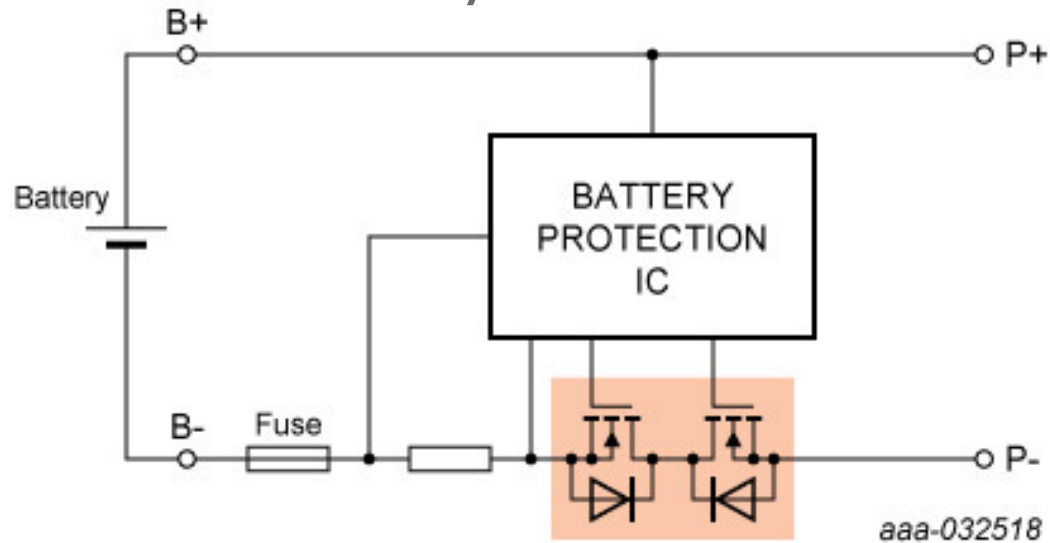
- Stein Hans Nesbakk
- Application Engineer



Applications with high current requirements

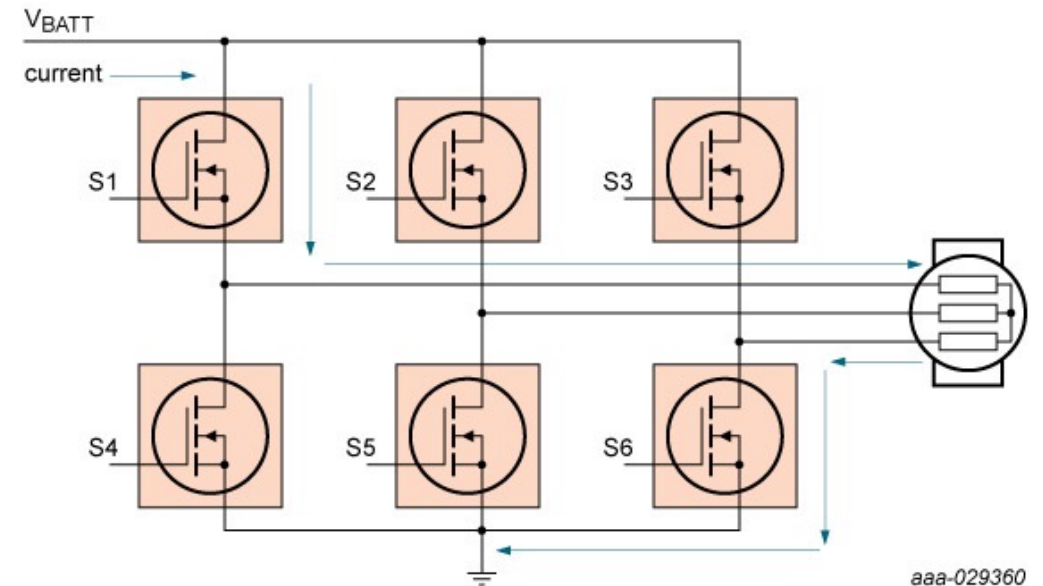
We're listing two, but more exist: E-Fuse, load switch, USB VBUS-switch etc...

Battery Isolation



Condition: over-current, short circuit ...

Motor Drive



Condition: Locked rotor

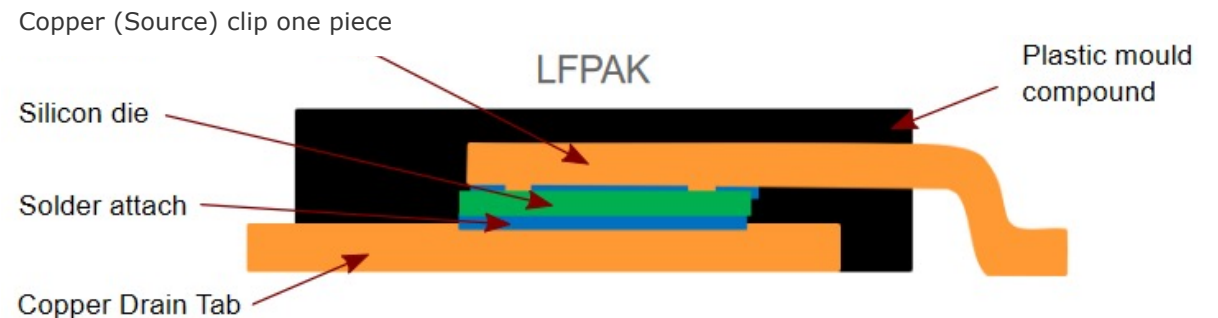
How power applications are evolving

- Power applications are becoming more demanding
 - Larger voltages
 - Larger currents
- Increased impact of application failures
 - Product reliability
 - Legal reliability
 - Safety
 - Brand reputation



What is ID rating?

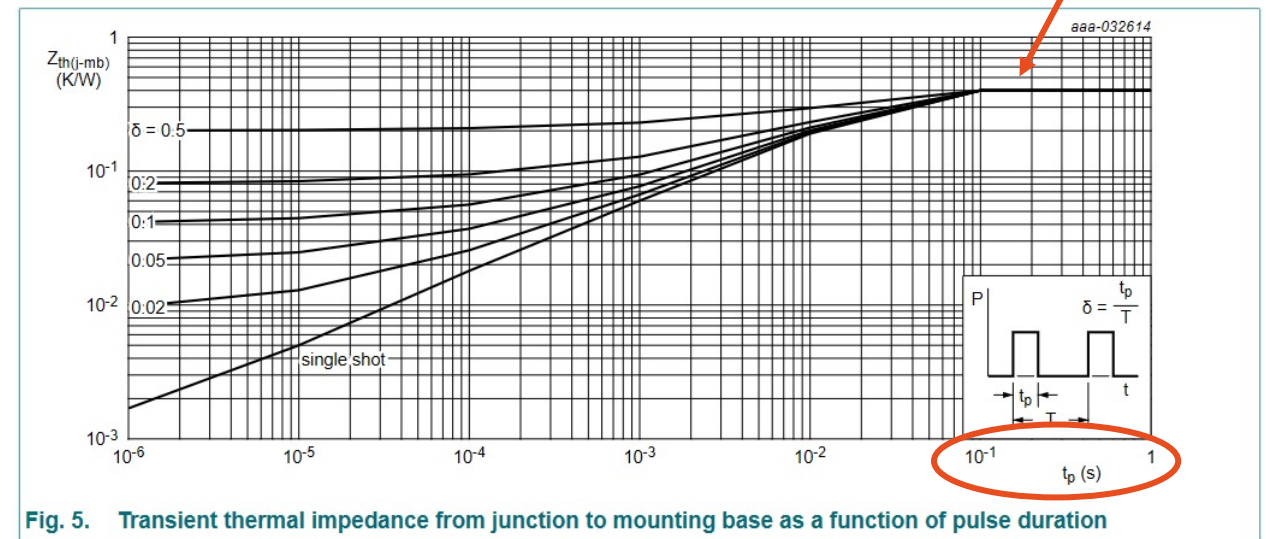
- Maximum continuous Drain-Source current the MOSFET can sustain while fully enhanced at $T_{mb}=25^{\circ}\text{C}$ and die at max junction temperature
- A single parameter that captures:
 - Thermal performance
 - Temperature rating
 - $R_{DS(on)}$
 - Silicon die resistance
 - Package resistance



What is considered continuous current?

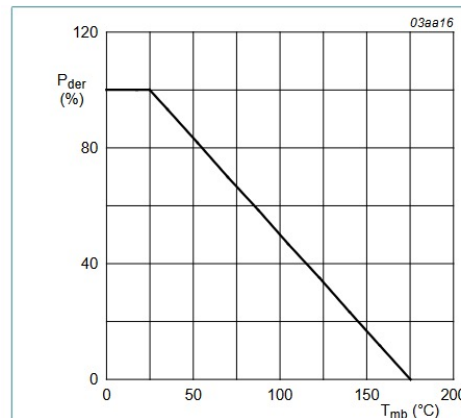
- When MOSFET reaches thermal stability ($>100\text{ms}$)
- Nexperia tests to $\geq 30\text{s}$
- Mounting base @25C (use of heatsink is necessary)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	0.35	0.4	K/W



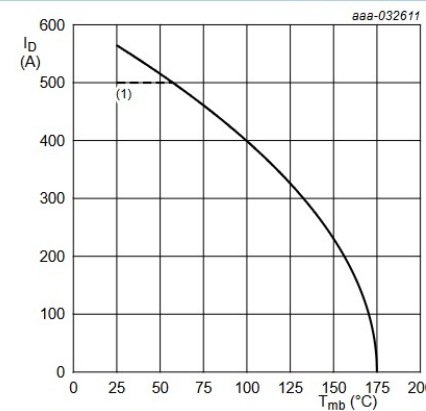
Drain current as a datasheet parameter

I_D	drain current	$V_{GS} = 10\text{ V}; T_{mb} = 25\text{ }^\circ\text{C}; \text{Fig. 2}$	[1]	-	500	A
I_{DM}	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}; T_{mb} = 25\text{ }^\circ\text{C}; \text{Fig. 3}$		-	2237	A
R_{Dson}	drain-source on-state resistance	$V_{GS} = 10\text{ V}; I_D = 25\text{ A}; T_j = 25\text{ }^\circ\text{C}; \text{Fig. 10}$		-	0.49	0.57 mΩ
		$V_{GS} = 4.5\text{ V}; I_D = 25\text{ A}; T_j = 25\text{ }^\circ\text{C}; \text{Fig. 10}$		-	0.65	0.82 mΩ



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ\text{C})}} \times 100\%$$

Fig. 1. Normalized total power dissipation as a function of mounting base temperature

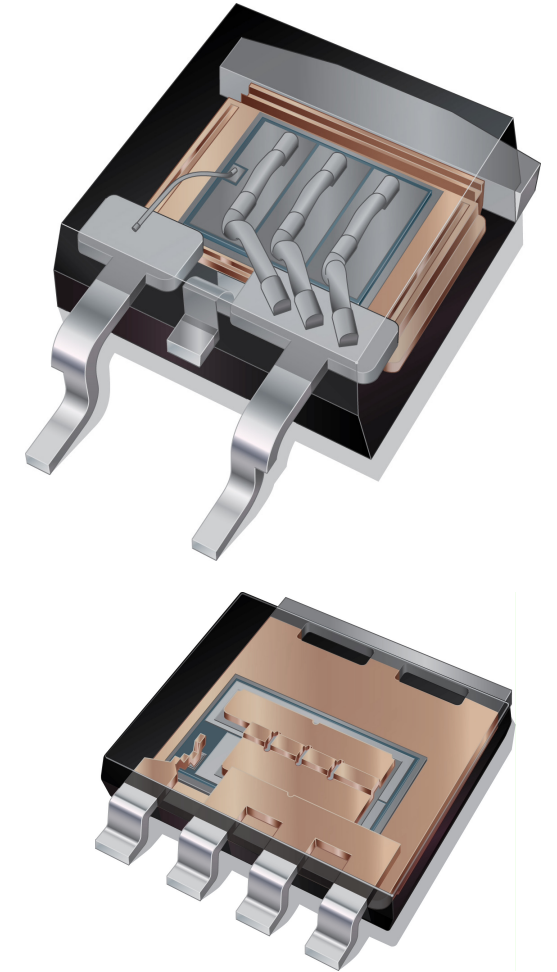


$V_{GS} \geq 10\text{ V}$
 (1) 500A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.

Fig. 2. Continuous drain current as a function of mounting base temperature

Device technologies and their impact

- ID max involves MOSFET parameters such as
 - Low R_{DSon}
 - Low R_{th}
 - $T_{j(max)}$ 175°C
 - Bond-wires & Cu-clip
 - Current spreading
 - Package thermals
 - Reduced manufacturing steps
 - Improves reliability
- ID captures these parameters directly and indirectly



From lab to application

How is this representative of a real circuit?

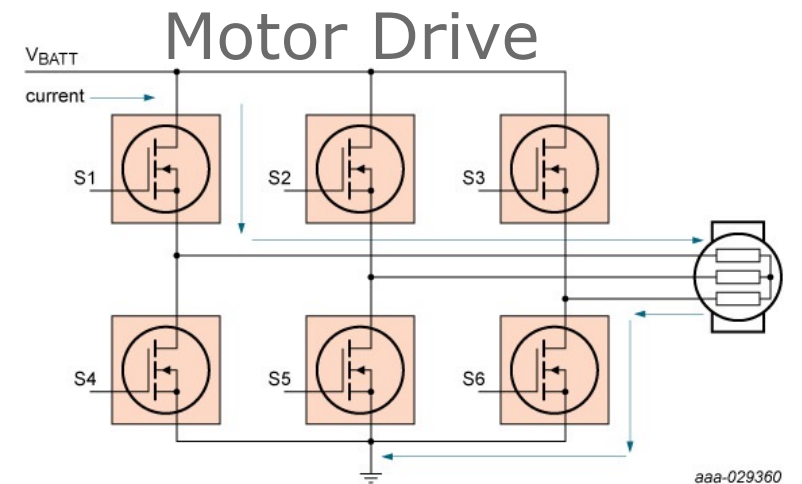
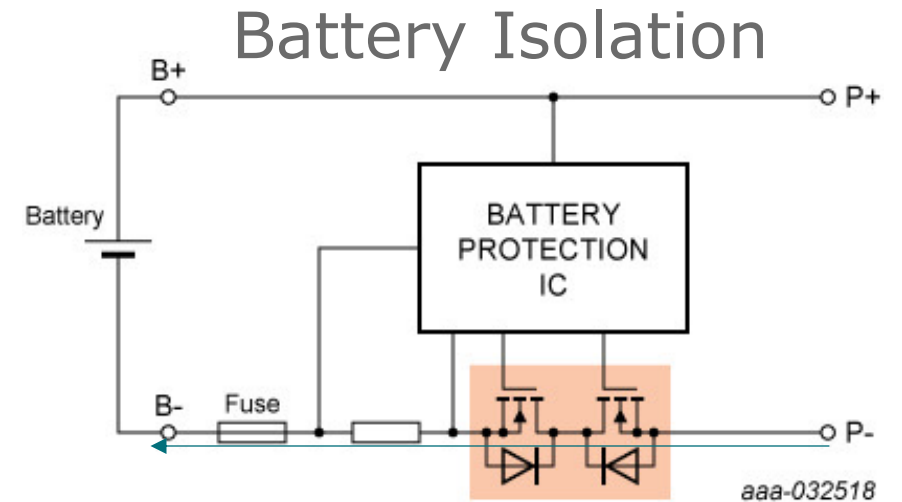
- Lab measurement conditions are consistent
- “Ideal” heatsink (T_{mb}) kept at 25°C
- T_j max can be reached
- Lab ≥ 30 seconds
- Measurement is verified in the lab
 - I_D max rating is determined when junction temperature reaches T_j max (175°C)
- Application conditions may vary
- I_D capability in applications is T_{mb} dependent
 - Application max current can be calculated from I_D max rating
- In an application, exceeding T_j max is not recommended
- System/application large surge current
 - 0.1-1sec considered DC for MOSFET
 - May not be considered DC for system
- Application will have safety margins and de-rating

I_D - Application benefit

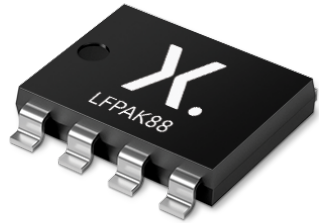
- Fully tested I_D rating on the datasheet
- I_D max rating is underpinned by:
 - Package technology
 - Silicon technology
 - Thermal performance
 - Manufacturing quality
- Gives a direct way of understanding complex MOSFET performance in an application when it matters the most

I_D in an application

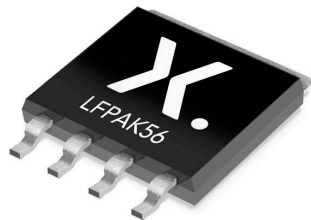
- E-fuse/Battery isolation
- Time between, over-current situation, its detection and reaction
- Motor Drive applications
- Time between rotor locks and control system reacts becomes critical
- I_D Max capability becomes critical in the time between high system current occurring and the system reacting
- Needs to switch off reliably
- Cable inductances - strong ruggedness (avalanche)
- Passes through linear mode when switching - Safe Operating Area



Nexperia products



LFPAK88	Current rating (DC)	Pulse current rating, I_{DM}
PSMNR55-40SSH	500A	2,237A
PSMN2R0-100SSF	267A	1,070A



LFPAK56	Current rating (DC)	Pulse current rating, I_{DM}
PSMNR51-25YLH	380A	2,174A
PSMN1R5-50YLH	200A	1159A
PSMN3R9-100YSF	120A	690A

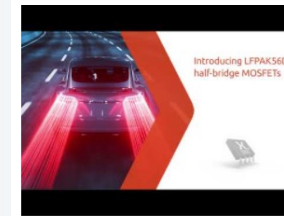
Nexperia Resources

- Please visit nexperia.com/mosfets
- Request Samples
 - Contact your local sales representative or distributor
 - Buy online from nexperia.com/shop

Videos



Understanding MOSFET datasheet parameters – Quick Learning



LFPAK56D half-bridge MOSFETs



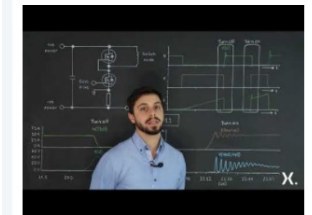
Design considerations with sub-milliohm MOSFETs – Quick Learning



Quick Learning: What is LFPAK56D half-bridge? (dual MOSFET ...



Quick Learning: PCB layout options for MOSFETs in low/medium ...



Quick Learning: Double pulse testing - assessing switching ...

Application Notes



AN90016

Maximum continuous currents in NEXPERIA LFPAK power MOSFETs

Rev. 1.1 — 3 September 2020

application note

Please share your
questions and insights

EFFICIENCY WINS.